

**A Study on Eliminating the 5.27% Production Loss Amounting to PHP  
47,807,334.64 in the process of wafer mounting and sawing of NCV78663  
LED Driver IC in probe area for the months of June to November 2013**

A Practicum Study presented to the Faculty of the  
College of Engineering Architecture and Technology

De La Salle University – Dasmariñas

Dasmariñas, Cavite

In Partial Fulfillment  
of the Requirements for the Degree in  
Bachelor of Science in Industrial Engineering

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March 2014

## ABSTRACT

On Semiconductor has the broadest selection of energy efficient solutions for a variety of end markets. Its products help manage power, extend battery life, protect sensitive circuits from electromagnetic and electrostatic discharge and help convert and regulate power in the products being used everyday. The researcher has chosen the production of NCV78663 LED Driver IC to be the focus of the study. The product however experiences problems regarding to its inability to reach the target output for the last months. The researcher has found out what the causes are that makes NCV78663 LED Driver IC experience a production loss. The objective of this study is to eliminate the causes that are being experienced by the company for the past six months. As the training and research go along, the researcher was able to come up with alternative course of actions which can help solve these problems.

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